



TIP TINNER

INTERFLUX®
ELECTRONICS N.V.



Technical data Tip Tinner

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Page 1



Soldering tip tinner for hand soldering irons

Description:

The Interflux® **TIP TINNER** is designed to keep wettable soldering tips in a good condition.

It cleans off carbonized flux residues and simultaneously re-tins oxidized soldering tips of hand (de)-soldering equipment.

The Interflux® **TIP TINNER** does not contain halogens or abrasive materials that can damage the surface of the soldering tip.

Correct use of the **TIP TINNER** can increase the life time of soldering tips substantially.

A clean soldering tip gives better heat transfer and will optimize the takt times in a hand soldering process.

Application:

After the soldering operation, the soldering tip is dipped into the **TIP TINNER** and moved gently around until wetting of the tip has occurred. After that, the excess solder is wiped off on a damp sponge. It is advisable not to use cleaning tools, like metallic sponges, scraping tools, abrasive tip tinner, ... as they may damage the

Physical and chemical properties:

Specific density	: 1.704 g/ml ± 0.1
Colour	: grey
Odour	: mild
Solubility in water	: insoluble
Alloy	: Sn99,3Cu0,7

surface of the soldering tip. This initial damage can quickly lead to the destruction of the soldering tip, especially with lead-free alloys.

To enhance the cleaning of heavily oxidised soldering tips, lower the tip temperature to about 250°C-320°C.

It is advisable to use the Tip Tinner after the soldering operation, before putting it back into the holder.

The frequency of the cleaning can be adapted towards the needs of each individual process and will depend on the soldering temperature, the type of solder wire and the frequency of use.

Small emissions of smoke are inherent to the process. As for any hand soldering operation, an air extraction is advised.



More information:

Test results P.2

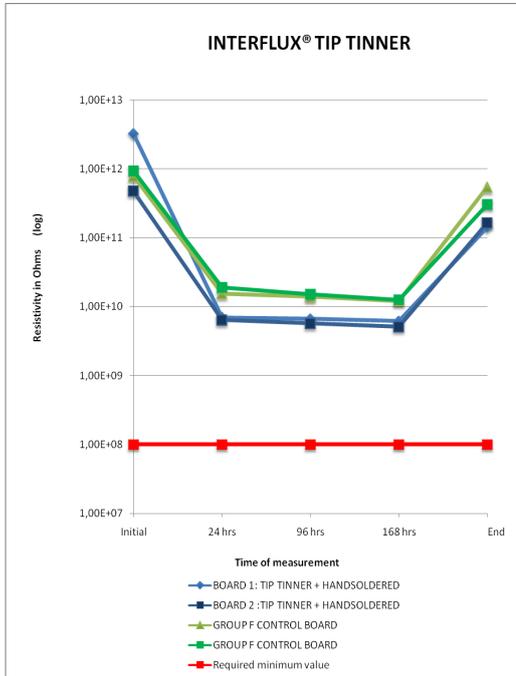
Packaging P.2

Key advantages:

- Easy applicable
- Efficient cleaning action
- Faster soldering due to better heat transfer
- Increased tip life
- Absolutely halogen free



Test results:



Surface Insulation Resistance test (SIR):

according to J-STD-004A, IPC-TM-650 Method 2.6.3.3

For this test, the soldering tip was dipped into the Tip Tinner, excess solder was wiped off on a damp sponge and the comb patterns were soldered with a no-clean, halogen free, lead-free solder wire.

Result : Pass

Packaging:

The **TIP TINNER** is available in the following packages:

30 g metal can

Trade name: **Interflux® Tip Tinner**

D i s c i m e r

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Product information in other European languages can be obtained at Interflux® Electronics NV, 9042 Gent.

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